TOSHIBA BIPOLAR DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

# TD62703PG, TD62703FG

#### 6CH HIGH VOLTAGE SOURCE DRIVER

The TD62703PG, TD62703FG is comprised of six source current Transistor Array.

These drivers are specifically designed for fluorescent display applications.

For proper operation, the substrate (SUB) must be connected to the most negative voltage.

This devices are a product for the Pb free(Sn-Ag).

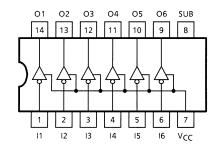
#### **FEATURES**

 $\begin{array}{ll} \bullet & \mbox{High output voltage} & : \ \mbox{V}_{CC}, \mbox{V}_{OUT} = 60 \ \mbox{V (Min)} \\ \bullet & \mbox{Output current (single output)} & : \ \mbox{I}_{OUT} = -50 \ \mbox{mA (Max)} \\ \end{array}$ 

• Input resistor :  $RIN = 2.7 \text{ k}\Omega$ 

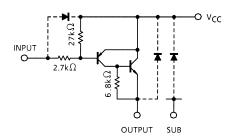
Package type-PG : DIP-14 pinPackage type-FG : SOP-14 pin

#### PIN CONNECTION (TOP VIEW)

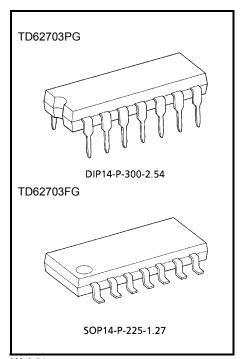


# DIP14-P-300-2.54 : 1.11 g (Typ.) SOP14-P-225-1.27 : 0.16 g (Typ.)

### **SCHEMATICS (EACH DRIVER)**



Note: The input and output parasitic diodes cannot be used as clamp diodes.



# MAXIMUM RATINGS (Ta = 25°C)

CHARACTER	RISTIC	SYMBOL	RATING	UNIT	
Supply Voltage		V <sub>SUB</sub>	V <sub>CC</sub> - 60	V	
Output Sustaining Volta	age	V <sub>OUT</sub>	V <sub>CC</sub> - 60	٧	
Input Voltage		V <sub>IN</sub>	-30~0.5	V	
Output Current		l <sub>OUT</sub>	-50	mA / ch	
Input Current		I <sub>IN</sub>	10	mA	
Power Dissipation	PG	D= (Note 2)	1.0	W	
	FG	P <sub>D</sub> (Note 2)	0.625 (Note 1)		
Operating Temperature		T <sub>opr</sub>	-40~85	°C	
Storage Temperature		T <sub>stg</sub>	-55~150	°C	

Note 1: On Glass Epoxy PCB (50 × 50 ×1.6 mm Cu 50%)

Note 2: Delated above 25°C in the proportion 8.0mW / °C (PG Type), 5.0mW / °C (FG Type).

# RECOMMENDED OPERATING CONDITIONS ( $Ta = -40-85^{\circ}C$ )

CHARAC <sup>*</sup>	TERISTIC	SYMBOL	CONDITION	MIN	TYP.	MAX	UNIT
Supply Voltage		$V_{SUB}$		V <sub>OUT</sub>	_	-55	V
Output Sustaining Voltage		V <sub>OUT</sub>		0	_	V <sub>SUB</sub>	V
Output Current		l <sub>OUT</sub>	V <sub>CC</sub> = 0 V	0	_	-40	mA / ch
Input Voltage		V <sub>IN</sub>		0	_	-7.0	V
Power Dissipation	PG	P <sub>D</sub>	_	_	_	0.36	W
	FG	י ט	On PCB (Note)	_	_	0.325	• • •

Note: On Glass Epoxy PCB (50 × 50 ×1.6 mm Cu 30%)

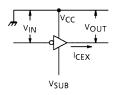
# **ELECTRICAL CHARACTERISTICS (Ta = 25°C)**

CHARAG	CTERISTIC	SYMBOL	TEST CIR- CUIT	TEST CONDITION	MIN	TYP.	MAX	UNIT
Output Leakage Current		I <sub>CEX</sub>	1	V <sub>CC</sub> = 0 V, V <sub>IN</sub> = 0 V V <sub>OUT</sub> = -55 V	_	_	-100	μA
Collector-Emitter Saturation Voltage		V <sub>CE (sat)</sub>	2	I <sub>IN</sub> = -1 mA, I <sub>OUT</sub> = -40 mA	_	_	-2.5	V
DC Current Transfer Ratio		h <sub>FE</sub>	2	$V_{CE} = -5.0 \text{ V}, I_{OUT} = -40 \text{ mA}$	100	_	_	_
Input Current	Output On	V <sub>IN (ON)</sub>	3	$V_{CC} = 0 \text{ V}, V_{IN} = -5.1 \text{ V}$	_	-1.7	-2.4	mA
	Output Off	V <sub>IN (OFF)</sub>	3	_	_	_	10	μA
Input Voltage	Output On	V <sub>IN (ON)</sub>	4	V <sub>CC</sub> = 0 V	-3.0	_	_	V
	Output Off	V <sub>IN</sub> (OFF)			_	_	-0.44	
Turn-On Delay	PG	ton			_	1	_	- µs
	FG	¹ON		$V_{CC} = 0 \text{ V},$ $V_{SUB} = V_{OUT} = -55 \text{ V}$ $R_{L} = 1.4 \text{ k}\Omega, C_{L} = 15 \text{ pF}$	_	0.5	_	
Turn-Off Delay	PG	ton	t <sub>ON</sub>		_	2	_	- µs
	FG	¹ON			_	1	_	

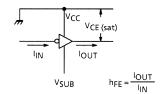
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#### **TEST CIRCUIT**

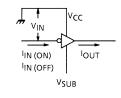
## 1. I<sub>CEX</sub>



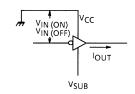
## 2. VCE (sat), hFE



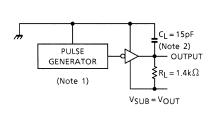
## 3. I<sub>IN</sub> (ON), I<sub>IN</sub> (OFF)

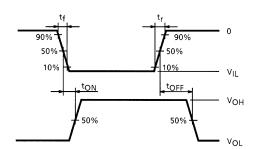


## 4. VIN (ON), IIN (OFF)



#### 5. ton, toff





Note 1: Pulse width 50 µs, Duty Cycle 10%

Output Impedance 50  $\Omega$ ,  $t_r \le 10$  ns,  $t_f \le 5$  ns

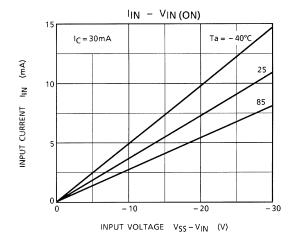
Note 2: C<sub>L</sub> includes probe and jig capacitance.

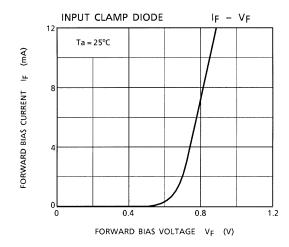
## **PRECAUTIONS for USING**

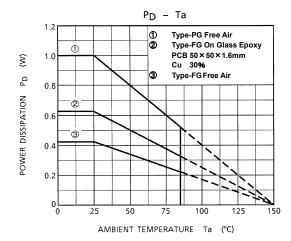
This IC does not integrate protection circuits such as overcurrent and overvoltage protectors.

Thus, if excess current or voltage is applied to the IC, the IC may be damaged. Please design the IC so that excess current or voltage will not be applied to the IC.

Utmost care is necessary in the design of the output line,  $V_{CC}$  and GND (SUB) line since IC may be destroyed due to short–circuit between outputs, air contamination fault, or fault by improper grounding.

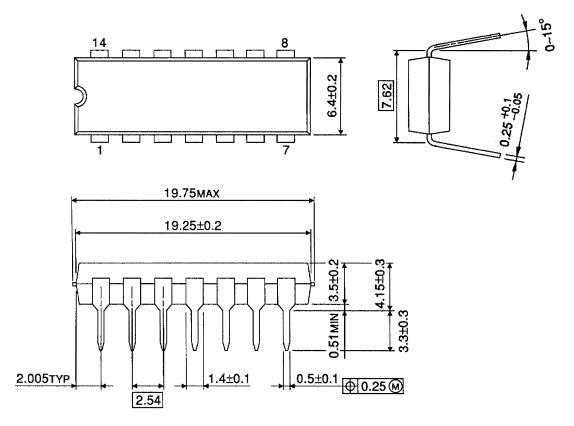






# **PACKAGE DIMENSIONS**

DIP14-P-300-2.54 Unit: mm



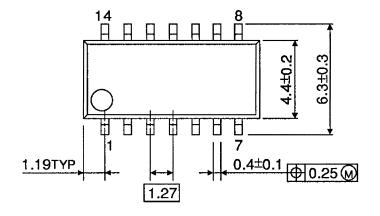
Weight: 1.11 g (Typ.)

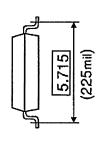
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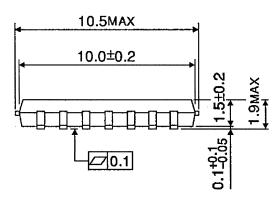
# **PACKAGE DIMENSIONS**

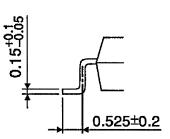
SOP14-P-225-1.27

Unit: mm









Weight: 0.16 g (Typ.)

About solderability, following conditions were confirmed

- Solderability
  - (1) Use of Sn-63Pb solder Bath
    - · solder bath temperature = 230°C
    - · dipping time = 5 seconds
    - · the number of times = once
    - · use of R-type flux
  - (2) Use of Sn-3.0Ag-0.5Cu solder Bath
    - · solder bath temperature = 245°C
    - dipping time = 5 seconds
    - · the number of times = once
    - · use of R-type flux

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